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European PIC Company with a global reach LIGENTEC key facts



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Commercial Offering

Seamless journey from Idea to Volumes 从想法到量产无缝衔接

Entry: R&D & Prototyping Open access, low barrier



Fast prototyping

- Established technology
- Fixed layer stack
- Extensive PDK
- Regular MPW runs
- Custom runs
- Design / layout support
- Characterization
- Packaging support

Optimize: Development High flexibility & competence



Custom PIC Developments

- Engineering studies
- Layer stack adaptation
- Custom integrations

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Early technology access

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Manufacturing: Supply Quality and guarantee



Pilot Fabrication

- Pilot and niche quantities Volume Fabrication
- Large volumes
- · High-capacity wafer fab
- Fully automated testing
- Automotive quality system

Material Choice **Benefits of Silicon Nitride**

Large transparency window: 400 – 4'000 nm Reference Silicon: 1'100 – 4'000 nm

Low propagation loss: < 1dB/m

Reference Silicon: 50-1000 dB/m

High optical power: > 5 W per waveguide (10⁹ W/cm²) Reference Silicon: 0.1 W per waveguide

Scalable to volume

Non exotic material





required for many applications





Data Center



Our mission Our focus is to bring PICS into products



Provide lowest loss **Passive** Integrated Photonics at scale



无源低损耗SiN光波导+调制器/探测器 ■→ 产品



Bring PICs into products 'Let's PIC it'



Hybrid Integration example Tunable Narrow Linewidth Lasers



LIGENTEC's capability to design, layout and fabrication





Y.Guo et al., IEEE Photonics Journal (2021) C.Liu et al., JLT (2022) Zia et al., arXiv 2211.02135 (2022)

Narrow Linewidth External Cavity Lasers

Linewidth: <3kHz SMSR: -70dB Max power: 34mW Tuning: 58.5nm SiN – The platform for heterogeneous integration

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Use SiN as base platform for general circuitry

- Comprehensive PDK
- Standard I/Os
- Scalable to volume

Add materials as required by application



The next step – enhance the SiN PIC platform Heterogeneous integration of modulators (GHz)

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Valdez et al., Optica 10 (2023)



The next step – enhance the SiN PIC platform Integration of photodiodes





Summary Low Loss SiN - Platform Overview

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